BY329X series

GENERAL DESCRIPTION

Glass-passivated double diffused rectifier diodes in a full pack plastic envelope featuring low forward voltage drop, fast reverse recovery and soft recovery characteristic. The devices are intended for use in TV receivers, monitors and switched mode power supplies.

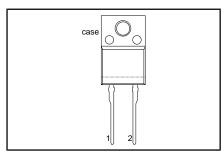
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
	BY329X	-800	-1000	-1200	
V_{RRM}	Repetitive peak reverse voltage	800	1000	1200	V
I _{F(AV)}	Average forward current	8	8	8	Α
I _{FSM}	Non-repetitive peak forward current	65	65	65	А
t _{rr}	Reverse recovery time	145	145	145	ns

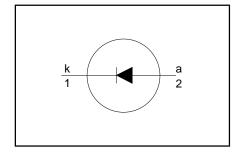
PINNING - SOD113

PIN	PIN DESCRIPTION	
1	cathode	
2	anode	
case	isolated	

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V _{RSM}	Non-repetitive peak reverse voltage		-	-800 800	-1000 1000	-1200 1200	V
$egin{array}{c} V_{RRM} \ V_{RWM} \end{array}$	Repetitive peak reverse voltage Crest working reverse voltage		- -	800 600	1000 800	1200 1000	V V
I _{F(AV)}	Average forward current ¹	square wave; $\delta = 0.5$; $T_{hs} \le 83$ °C	-		8		Α
		sinusoidal; a = 1.57; $T_{hs} \le 90 ^{\circ}C$	-		7		Α
I _{F(RMS)}	RMS forward current		-		11		Α
I _{FRM}	Repetitive peak forward current	$t = 25 \mu s$; $δ = 0.5$; $T_{hs} \le 83 °C$	-		16		Α
I _{FSM}	Non-repetitive peak forward	t = 10 ms	-		65		Α
1 0.11	current.	t = 8.3 ms sinusoidal; T _j = 150 °C prior to surge; with reapplied V _{RWM(max)}	-		71		А
l ² t	I ² t for fusing	t = 10 ms	-		28		A^2s
T _{stg}	Storage temperature		-40		150		,C
T _j	Operating junction temperature		-		150		°Č

May 1995 1 Rev 1.000

¹ Neglecting switching and reverse current losses.

Philips Semiconductors Product specification

Rectifier diodes fast, soft-recovery

BY329X series

ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from both terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65% ; clean and dustfree	ı		2500	V
C _{isol}	Capacitance from both terminals to external heatsink	f = 1 MHz	1	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	heatsink	with heatsink compound without heatsink compound in free air.	1 1 1	- - 55	4.8 5.9 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

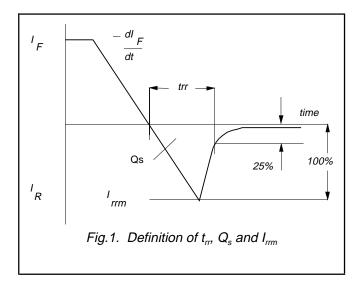
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{F}	Forward voltage	I _F = 20 A	-	1.5	1.85	V
I _R	Reverse current	$\dot{V}_R = V_{RWM}$; $T_j = 125 ^{\circ}C$	-	0.1	1.0	mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Reverse recovery charge	$\begin{array}{l} I_F = 1 \text{ A; } V_R \geq 30 \text{ V; } -dI_F/dt = 50 \text{ A/}\mu\text{s} \\ I_F = 2 \text{ A; } V_R \geq 30 \text{ V; } -dI_F/dt = 20 \text{ A/}\mu\text{s} \\ I_F = 2 \text{ A; } -dI_F/dt = 20 \text{ A/}\mu\text{s} \end{array}$	1 1 1	125 0.5 50	145 0.7 60	ns μC A/μs

BY329X series



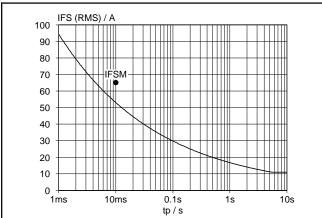


Fig.4. Maximum non-repetitive rms forward current. $I_F = f(t_p)$; sinusoidal current waveform; $T_j = 150^{\circ}\text{C}$ prior to surge with reapplied V_{RWM} .

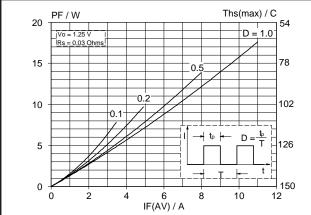


Fig.2. Maximum forward dissipation, $P_F = f(I_{F(AV)})$; square wave current waveform; parameter D = duty $cycle = t_p/T$.

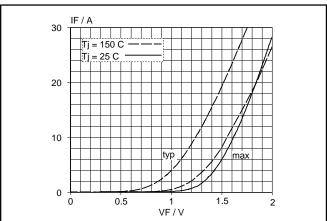


Fig.5. Typical and maximum forward characteristic; $I_F = f(V_F)$; parameter T_i

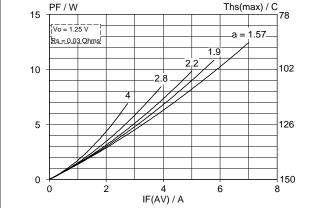
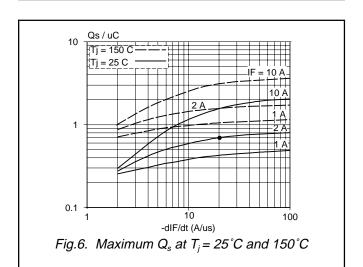


Fig.3. Maximum forward dissipation, $P_F = f(I_{F(AV)})$; sinusoidal current waveform; parameter a = form factor $= I_{F(RMS)}/I_{F(AV)}$.



BY329X series

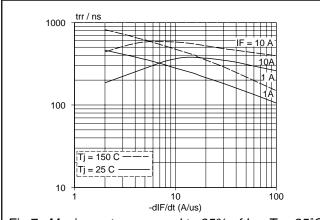
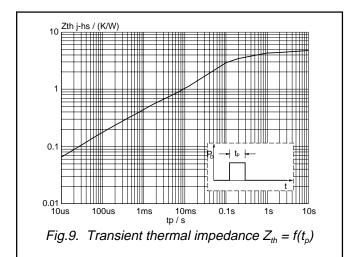


Fig.7. Maximum t_{rr} measured to 25% of I_{rrm} ; $T_j = 25^{\circ}C$ and 150°C



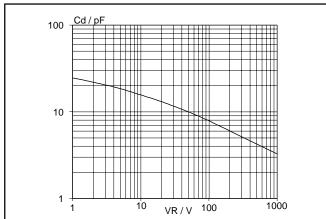
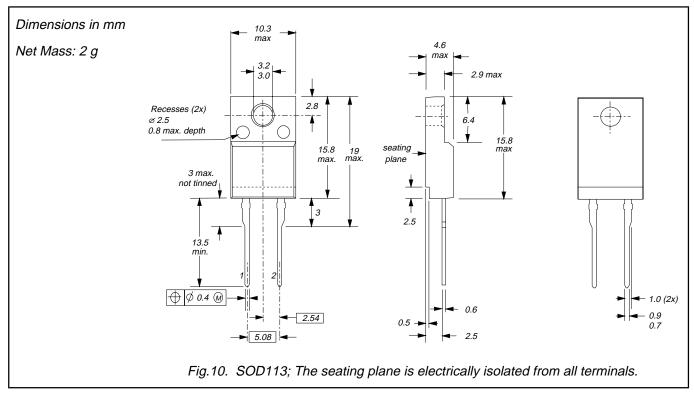


Fig.8. Typical junction capacitance C_d at f = 1 MHz, $T_j = 25^{\circ}C$

BY329X series

MECHANICAL DATA



Notes

- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

BY329X series

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 1996

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.